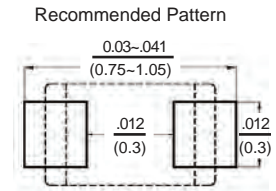
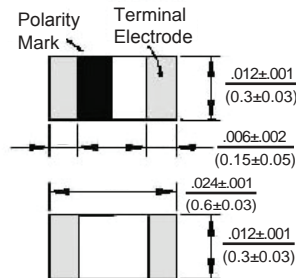




0201 High Frequency Ceramic Chip Inductor HFC02



Dimensions: $\frac{\text{Inches}}{\text{(mm)}}$



Allied Part Number	Inductance (nh) @100MHz	Tolerance (%)	Q @100MHz	SRF (MHz)	DCR Max. (Ω)	IDC Max. (mA)
HFC02-1N0S-RC	1.0	0.3nh	4	10000	0.11	470
HFC02-1N2S-RC	1.2	0.3nh	4	10000	0.12	450
HFC02-1N5S-RC	1.5	0.3nh	4	8000	0.13	430
HFC02-1N8S-RC	1.8	0.3nh	4	8000	0.16	390
HFC02-2N0S-RC	2.0	0.3nh	4	8000	0.17	380
HFC02-2N2S-RC	2.2	0.3nh	4	8000	0.19	360
HFC02-2N4S-RC	2.4	0.3nh	4	8000	0.20	350
HFC02-2N7S-RC	2.7	0.3nh	4	7200	0.21	340
HFC02-3N0S-RC	3.0	0.3nh	4	6200	0.22	330
HFC02-3N3S-RC	3.3	0.3nh	4	6200	0.23	320
HFC02-3N6S-RC	3.6	0.3nh	4	5200	0.25	310
HFC02-3N9S-RC	3.9	0.3nh	4	5000	0.27	300
HFC02-4N3S-RC	4.3	0.3nh	4	4750	0.30	280
HFC02-4N7S-RC	4.7	0.3nh	4	4750	0.30	280
HFC02-5N1S-RC	5.1	0.3nh	4	4100	0.33	270
HFC02-5N6S-RC	5.6	0.3nh	4	4100	0.36	260
HFC02-6N2S-RC	6.2	0.3nh	4	4100	0.38	250
HFC02-6N8J-RC	6.8	5	4	3750	0.39	250
HFC02-7N5J-RC	7.5	5	4	3750	0.41	240
HFC02-8N2J-RC	8.2	5	4	3300	0.45	230
HFC02-9N1J-RC	9.1	5	4	3300	0.48	220
HFC02-10NJ-RC	10	5	4	3000	0.51	220
HFC02-12NJ-RC	12	5	4	2800	0.68	190
HFC02-15NJ-RC	15	5	4	2600	0.71	180
HFC02-18NJ-RC	18	5	4	2500	0.81	170
HFC02-22NJ-RC	22	5	4	2400	1.00	150
HFC02-27NJ-RC	27	5	4	2000	1.35	120
HFC02-33NJ-RC	33	5	4	1900	1.47	110
HFC02-39NK-RC	39	5	4	1600	1.72	100
HFC02-47NJ-RC	47	5	4	1400	1.90	100
HFC02-56NJ-RC	56	5	4	1300	2.27	80
HFC02-68NJ-RC	68	5	4	1100	2.66	80
HFC02-82NJ-RC	82	5	4	1050	3.37	70
HFC02-R10J-RC	100	5	4	1050	3.74	60

All specifications subject to change without notice.

Features

- 0201 EIA size for high board density applications.
- Excellent SRF characteristics exceeding 10GHz
- Expanded inductance range

Electrical

Inductance range: 1.0nh to 100nh

Tolerance: 1.0nH to 6.2nH=±.3nH, 6.8nH to 100nH=±±%

Test Frequency: 100MHz

Operating Temp: -55°C to +125°C

Rated Current: The current at which the temp will not ride by more than 30°C. Part temperature should not exceed 125°C including temperature rise.

Resistance to solder heat:

Pre heat: 150°C. 1min.

Solder composition:

Sn/Ag3.0/Cu.0.5

Solder temp: 260°C±5°C

Immersion time: 10 sec ± 1 sec.

Test Equipment:

L/Q: E4991A Agilent with 16197A

DCR: HP4338B/CH502BC

SRF: HP E4991A/HP19196C

Physical

Packaging: 15000 pieces per 7 inch reel.